

Transient Voltage Suppressor

Features

- Low clamping voltage
- IEC 61000-4-2(ESD)±15KV(air), ±8KV(contact)
- Small package:SMB
- Moisture sensitivity level: Level 1
- Max surge capability: 4KV@10/700us

Exterior



SMB

Application Information

- POE
- DC-48V

Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

Part Number and Electrical Parameter

Part Number	I _R @V _R		V _{BR} @I _t		VC@10/700us ^①	Surge capability@10/700us ^①	
	μA	V	V		V	KV	
	MAX		MIN	MAX	MAX	MAX	
BV-SMBJ58C2H	1	58	62.4	71.2	1	85	4

Absolute maximum ratings measured at T= 25°C RH = 45%-75% (unless otherwise noted).

①Ri=40Ω

Part Number System

BV SMBJ 58 C 2 H

(1) (2) (3) (4) (5) (6)

(1) BencentTransient Voltage Suppressor

(2) SMB Package

(3) V_R=58V

(4) Bidirectional polar

(5)2 chip

(6)High surge capability

Mark



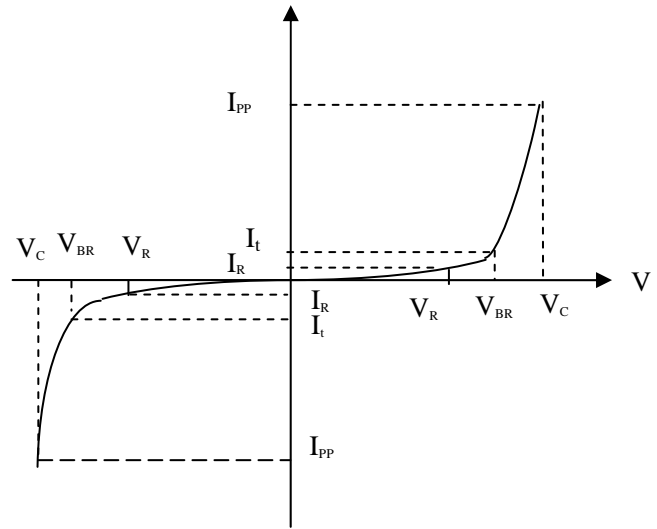
B58C2: Part Number

Transient Voltage Suppressor

Version: A1 2016-8-8

V-I Curve

Parameters	Definition
V_C	Clamping Voltage
I_{PP}	Surge Waveform
V_R	Stand-off Voltage
V_{BR}	Breakdown Voltage
I_R	Reverse Leakage Current
I_t	Test Current
P_{pp}	Peak Pulse Power Dissipation



Thermal Considerations

symbol	Parameter	Value	Unit
T_J	Operating Junction Temperature Range	-55 to +150	°C
T_S	Storage Temperature Range	-55 to +150	°C

Environmental Characteristics

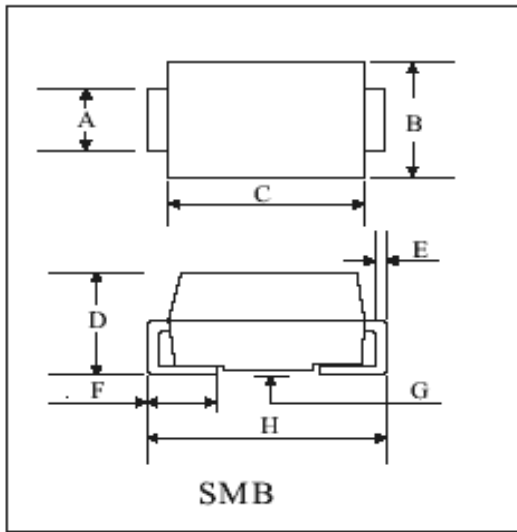
Testing items	Technical standards
High Temperature Reverse Bias Test	Temperature: $150 \pm 3^\circ\text{C}$ Bias= $80\%V_{DRM}$ Time: 168H
High Temperature Life Test	Temperature: 150°C Time: 168H
High-low Temperature Cycle Test	Temperature: From -40°C to 125°C Dwell time : 30min, 10cycles
High Temperature & High Humidity Test	Temperature: 85°C Humidity: 85% Time: 168H
Pressure Cooker Test	Temperature: 121°C , 2atm. Humidity: 100% Time: 24H
Resistance of Soldering Heat	Temperature: $260 \pm 5^\circ\text{C}$ Time of dip soldering: 10s, 3times

Note: The above testing items can be specified by customer's special request

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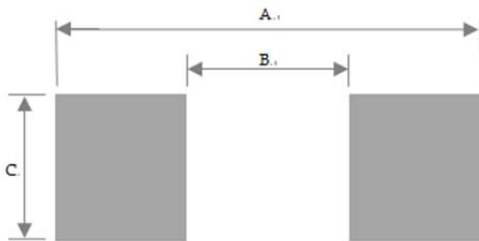
Version: A1 2016-8-8

Product Dimensions



REF.	mm	inch
A	1.85--2.15	0.073--0.085
B	3.45--3.75	0.138--0.148
C	4.35--4.65	0.171--0.183
D	2.10--2.60	0.083--0.102
E	0.15--0.25	0.006--0.010
F	0.80--1.50	0.031--0.059
G	0.00--0.40	0.000--0.016
H	4.95--5.45	0.195--0.215

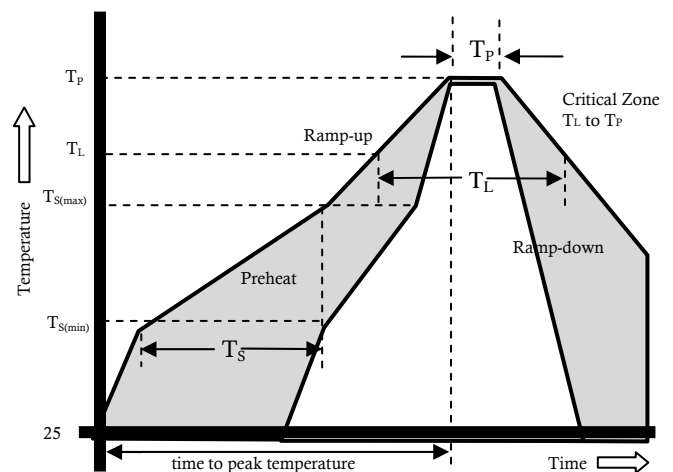
Recommended Soldering Pad



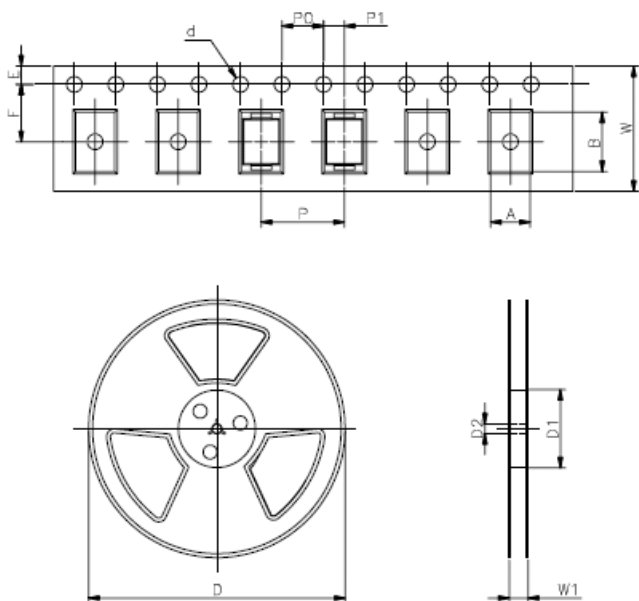
REF	mm	inch
A	5.45	0.215
B	2.45	0.097
C	2.15	0.085

Reflow Profile

Reflow Condition		Pb-Free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time (min to max)	60 – 180 secs
Average ramp up rate (Liquidus) T _{amp} (T _L) to peak		3°C/s max
T _{S(max)} to T _L - Ramp-up Rate		3°C/s max
Reflow	- Temperature (T _L) (Liquidus)	217°C
	- Temperature (T _L)	60 – 150 secs
Peak Temperature (T _P)		260±0/-5 °C
Time within 5°C of actual peak Temperature (T _P)		30secs
Ramp-down Rate		6°C/s max
Time 25°C to peak Temperature (T _P)		8 min max.
Do not exceed		260°C



Package Reel Information



REF	mm	inch
A	3.8+/-0.3	0.150+/-0.012
B	5.5+/-0.3	0.217+/-0.012
d	1.5+/-0.1	0.059+/-0.004
D	330+/-1	13+/-0.039
D1	72+/-3	2.835+/-0.118
D2	13+/-0.3	0.512+/-0.012
E	1.75+/-0.2	0.069+/-0.008
F	5.5+/-0.02	0.217+/-0.008
P	8.0+/-0.2	0.315+/-0.008
P0	4.0+/-0.2	0.157+/-0.008
P1	2.0+/-0.2	0.079+/-0.008
W	12.0+/-0.2	0.472+/-0.008
W1	18+/-2.0	0.709+/-0.079

Outline	Reel (pcs)	Per Carton (pcs)	Reel Diameters (mm)	Carton Size(mm)		
				L	W	H
Taping	3,000	24,000	330	360	360	380